

RELIABILITY REPORT
FOR
LM4051AEM3-1.2+
PLASTIC ENCAPSULATED DEVICES

July 1, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Conclusion

The LM4051AEM3-1.2+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The LM4050/LM4051 are precision two-terminal, shuntmode, bandgap voltage references available in fixed reverse breakdown voltages of 1.225V, 2.048V, 2.500V, 3.000V, 3.3V, 4.096V, and 5.000V. Ideal for space-critical applications, the LM4050/LM4051 are offered in the subminiature 3-pin SC70 surface-mount packages (1.8mm x 1.8mm), 50% smaller than comparable devices in SOT23 surface-mount package (SOT23 versions are also available). Laser-trimmed resistors ensure excellent initial accuracy. With a 50ppm/°C temperature coefficient, these devices are offered in three grades of initial accuracy ranging from 0.1% to 0.5%. The LM4050/LM4051 have a 60µA to 15mA shunt-current capability with low dynamic impedance, ensuring stable reverse breakdown voltage accuracy over a wide range of operating temperatures and currents. The LM4050/LM4051 do not require an external stabilizing capacitor while ensuring stability with any capacitive loads. The LM4050/LM4051 specifications are guaranteed over the temperature range of -40°C to +125°C.

II. Manufacturing Information

A. Description/Function:	50ppm/°C Precision Micropower Shunt Voltage References with Multiple Reverse Breakdown Voltages
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	July 26, 2002

III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0187
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250°C/W
K. Single Layer Theta Jc:	130°C/W

IV. Die Information

A. Dimensions:	30 X 31 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 155 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 3.1 \times 10^{-9}$$

$\lambda = 3.1$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B12 Process results in a FIT Rate of 3.13 @ 25C and 54.16 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF25 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

LM4051AEM3-1.2+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	155	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data